

## AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): Hiroyuki Nishi et al.

Docket No.

SKI.007D

Serial No.

09/893,455

Filing Date

June 29, 2001

Examiner

A. Ortiz

Group Art Unit

1732

Invention: TRANSFER MOLDING METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICES

TO THE COMMISSIONER FOR PATENTS:

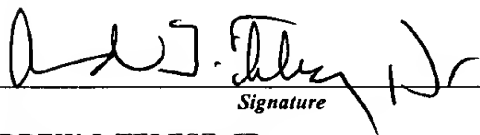
Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

## CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	12 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	4 -	4 =	0 x	\$86.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. \_\_\_\_\_ in the amount of \_\_\_\_\_
- ☐ A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.
- ☒ The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0238
- ☒ Any additional filing fees required under 37 C.F.R. 1.16.
- ☒ Any patent application processing fees under 37 CFR 1.17.

  
Signature

Dated: February 5, 2004

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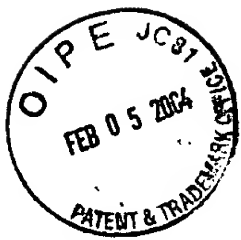
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Serial No. 09/893,455  
SKI.007D  
Amendment dated February 5, 2004

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re PATENT APPLICATION of

Hiroyuki Nishi et al.

Group Art Unit: 1732

Serial No.: 09/893,455

Examiner: A. Ortiz

Filed: June 29, 2001

Confirm. No.: 7179

For: TRANSFER MOLDING METHOD FOR MANUFACTURING SEMICONDUCTOR  
DEVICES

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**AMENDMENT UNDER 37 C.F.R. 1.116**

U.S. Patent and Trademark Office  
2011 South Clark Place  
Customer Window, **Mail Stop AF**  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202

Date: February 5, 2004

Sir:

In response to the Final Office Action dated November 6, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.